WL1835MOD C2PC Details

Revision 3.0

April 22, 2019

Revision Control

Author Name	Description	Revision	Date
Rizwan Murji	Initial Draft	1.0	Oct 31, 2017
Rizwan Murji	Updated Note	2.0	Jan 22, 2108
Rizwan Murji	Changed U.FL to antenna in Note	3.0	April 22, 2019

1. Introduction

The purpose of this document is to request a C2PC on our existing WL18MODGB modular certification (FCC ID: Z64 - WL18SBMOD, ISED ID: 451I-WL18SBMOD, test grades 01, 05, 31 and 35). The change will be to the OEM installation instructions to include a minimum cable loss. The parts in question can be seen below:

WL1801MOD	Model: WL18MODGB Test Grade:01 FCC ID:Z64-WL18SBMOD IC: 451I-WL18SBMOD R 201-135370 LTC: 1712115	**WL1805MOD**	Model: WL18MODGB Test Grade:05 FCC ID:Z64-WL18SBMOD IC: 451I-WL18SBMOD R 201-135370 LTC: 1712215
WL1831MOD	Model: WL18MODGB Test Grade:31 FCC ID:Z64-WL18SBMOD IC: 451I-WL18SBMOD R 201-135370 LTC: 1712315	**WL1835MOD**	Model: WL18MODGB Test Grade:35 FCC ID:Z64-WL18SBMOD IC: 451I-WL18SBMOD R 201-135370 LTC: 1712415

2. Summary

Our original filing was done with the WL18MODGB placed on the WL1835MOCOM8B evaluation board. The trace loss from the output of the main antenna to the U.FL connector is 1dBm as show in Figure 1 below.

Figure 1: WL18MODGB mounted on WL1835MODCOM8B EVM

Testing was also performed with the WL18MODGB Test grade 35 placed on the WL1837MODCOM8I evaluation board. During the testing a 1dB cable loss was included in the measurements as shown in Figure 2. Results of the test (to be supplied by Sporton) show no measureable difference in output power as the original grant.

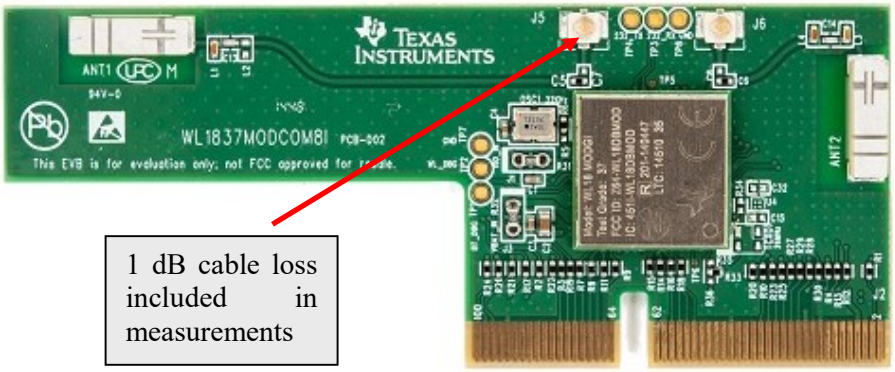

Figure 2: WL18MODGB mounted on WL1837MODCOM8B EVM

Based on the above information we are requesting that a C2PC be performed allowing customers to include an equivalent 1dB loss of any shape or form (such as trace, cable or 1-dB pi-pad loss) in their design and maintain the use of the current FCC and ISED IDs. The integrator guide provided to customers will be updated to reflect this with the following statement:

Note: at least an equivalent 1dB loss (in the form of trace, cable or 1-dB pi-pad loss) is required between the output of the WL18MODGB module and the antenna to be compliant with the current Z64- WL18SBMOD and 451I-WL18SBMOD module certification.

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